

## **In the Specification:**

Please make the following changes at the indicated locations in the specification:

Page 4, between lines 1 and 9, please make the following change:

The manufacturing process currently ~~under~~-used for press molding a glass body is limited by the sticking temperature  $T_0$ , at which the glass body adheres to the press mold. By applying a voltage across the glass body in the press mold it is possible now to work the glass body above the sticking temperature  $T_0$ . Thus the glass body can be brought to a higher temperature level and thus a lower viscosity at the beginning of the process, i.e. during heat up in the press mold. This leads to a shorter dwell time of the glass body in the press mold. The method can then be performed more rapidly and thus the manufacturing costs can be reduced.